

Figure 1
(prior art)

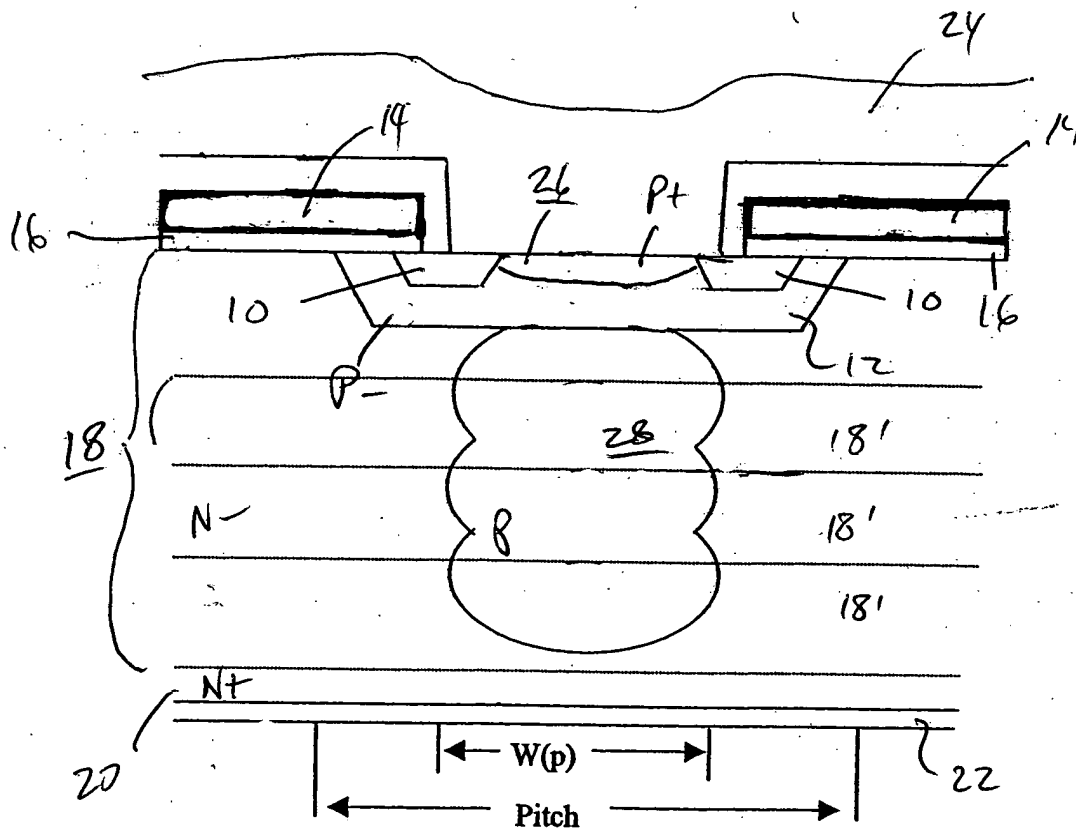


Figure 2
(prior art)

Figure 3
(prior art)

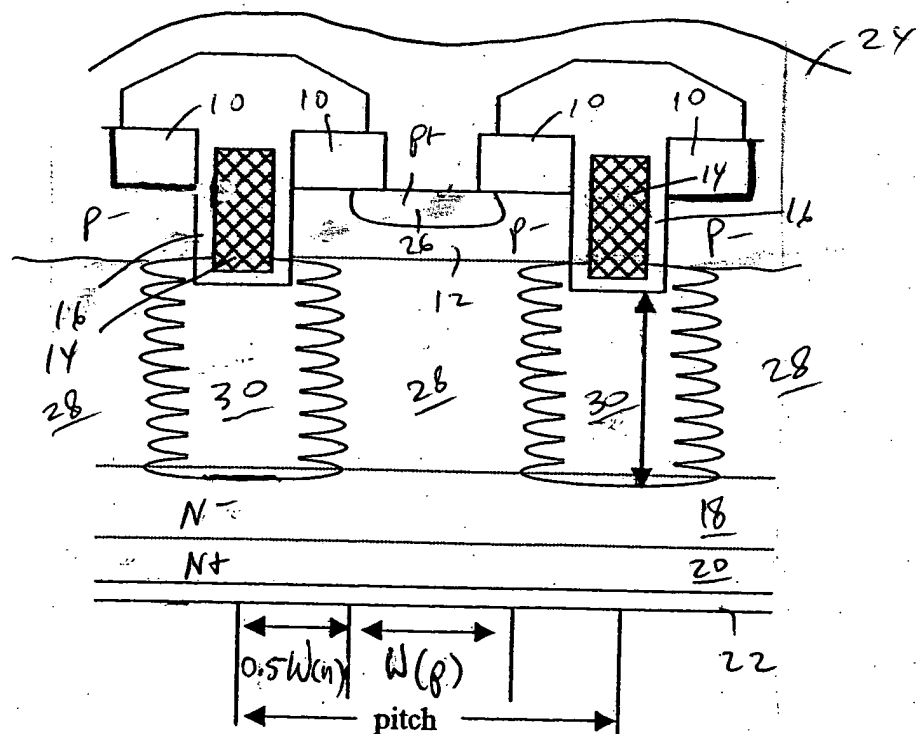


Figure 4

Hand-drawn cross-sectional diagram of a trench etching process. The diagram shows a central trench flanked by two side regions. The top layer is labeled "Photoresist" and the layer below it is "Trench Hard Mask". The trench is filled with a material labeled "40". The side regions are labeled "10", "12", "28", and "30". The bottom of the trench is labeled "18".

Figure 5B

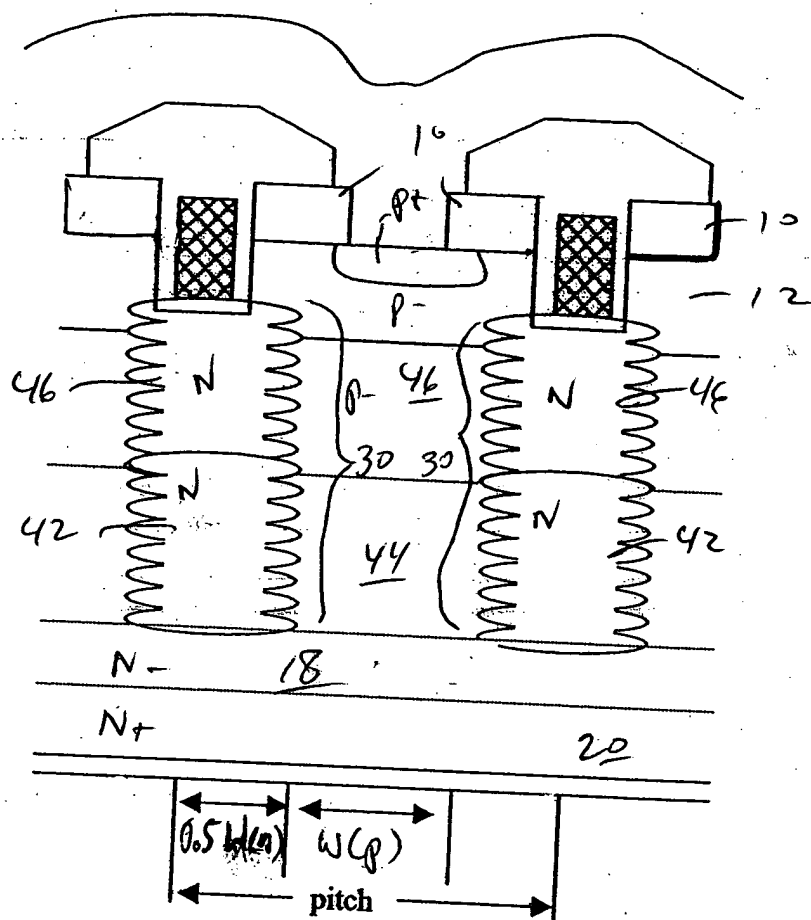


Figure 6